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Continuous Rate 8.5 Gbps to 11.3 Gbps Clock and Data Recovery IC with Integrated Limiting Amp/EQ

Data Sheet

ADN2917

FEATURES

- Serial data input: 8.5 Gbps to 11.3 Gbps
- No reference clock required
- Exceeds SONET/SDH requirements for jitter transfer/generation/tolerance
- Quantizer sensitivity: 9.2 mV p-p typical (limiting amplifier mode)
- Optional limiting amplifier and equalizer inputs
- Programmable jitter transfer bandwidth to support G.8251 OTN
- Programmable slice level
- Sample phase adjust
- Output polarity invert
- Programmable LOS threshold via I²C
- I²C to access optional features
- LOS alarm (limiting amplifier mode only)
- LOL indicator
- PRBS generator/detector
- Application-aware power
  - 352 mW at 8.5 Gbps, equalizer mode, no clock output
  - 430 mW at 11.3 Gbps, equalizer mode, no clock output
- Power supplies: 1.2 V, flexible 1.8 V to 3.3 V, and 3.3 V
- 4 mm × 4 mm 24-lead LFCSP

APPLICATIONS

- SONET/SDH OC-192, 10GFC, and 10GE and all associated FECs
- XFP, line cards, clocks, routers, repeaters, instruments
- Any rate regenerators/repeaters

GENERAL DESCRIPTION

The ADN2917 provides the receiver functions of quantization, signal level detect, and clock and data recovery for continuous data rates from 8.5 Gbps to 11.3 Gbps. The ADN2917 automatically locks to all data rates without the need for an external reference clock or programming. ADN2917 jitter performance exceeds all jitter specifications required by SONET/SDH, including jitter transfer, jitter generation, and jitter tolerance.

The ADN2917 provides manual or automatic slice adjust and manual sample phase adjusts. Additionally, the user can select a limiting amplifier or equalizer at the input. The equalizer is either adaptive or can be manually set.

The receiver front-end loss of signal (LOS) detector circuit indicates when the input signal level has fallen below a user-programmable threshold. The LOS detect circuit has hysteresis to prevent chatter at the LOS output. In addition, the input signal strength can be read through the I²C registers.

The ADN2917 also supports pseudorandom binary sequence (PRBS) generation, bit error detection, and input data rate readback features.

The ADN2917 is available in a compact 4 mm × 4 mm, 24-lead frame chip scale package (LFCSP). All ADN2917 specifications are defined over the ambient temperature range of −40°C to +85°C, unless otherwise noted.

FUNCTIONAL BLOCK DIAGRAM

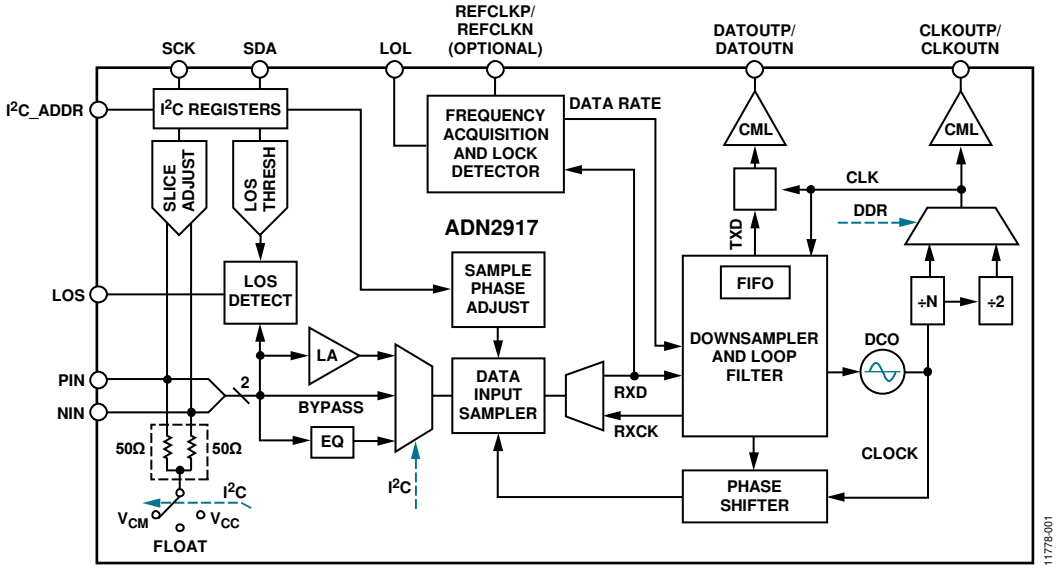

Figure 1.

Rev. A Document Feedback

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- ADN2905/ADN2913/ADN2915/ADN2917 Evaluation Board

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- ADN2917: Continuous Rate 8.5 Gbps to 11.3 Gbps Clock and Data Recovery IC with Integrated Limiting Amp/EQ Data Sheet

User Guides

- UG-877: ADN2905/ADN2913/ADN2915/ADN2917 Evaluation Board Setup and Applications

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- ADN2917 Material Declaration
- PCN-PDN Information
- Quality And Reliability
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TABLE OF CONTENTS

REVISION HISTORY

2/16—Rev. 0 to Rev. A

Changes to Figure 5 ... 9
Changes to Table 7 ... 13
Updated Outline Dimensions ... 32
Changes to Ordering Guide ... 32

5/14—Revision 0: Initial Version

SPECIFICATIONS

$T_A = T_{MIN}$ to T_{MAX}, VCC = VCC_{MIN} to VCC_{MAX}, VCC1 = $VCC1_{MIN}$ to $VCC1_{MAX}$, VDD = VDD_{MIN} to VDD_{MAX}, VEE = 0 V, input data pattern: PRBS $2^{23} - 1$, ac-coupled, I^2C register default settings, unless otherwise noted.

Table 1.

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
DATA RATE SUPPORT RANGE		8.5		11.3	Gbps
INPUT—DC CHARACTERISTICS					
Peak-to-Peak Differential Input[1]	PIN – NIN			1.0	V
Input Resistance	Differential	95	100	105	Ω
BYPASS PATH—CML INPUT					
Input Voltage Range	At PIN or NIN, dc-coupled, RX_TERM_FLOAT = 1 (float)	0.5		VCC	V
Input Common-Mode Level	DC-coupled (see Figure 32), 600 mV p-p differential, RX_TERM_FLOAT = 1 (float)	0.65		VCC − 0.15	V
Differential Input Sensitivity					
OC-192	AC-coupled, RX_TERM_FLOAT = 0 (V_{CM} = 1.2 V), bit error rate (BER) = 1×10^{-10}		200		mV p-p
8GFC[2]	Jitter tolerance scrambled pattern (JTSPAT), ac-coupled, RX_TERM_FLOAT = 0 (V_{CM} = 1.2 V), BER = 1×10^{-12}		200		mV p-p
LIMITING AMPLIFIER INPUT PATH					
Differential Input Sensitivity					
OC-192	BER = 1×10^{-10}		9.2		mV p-p
8GFC[2]	JTSPAT, BER = 1×10^{-12}		8.3		mV p-p
10.3125 Gbps	JTSPAT, BER = 1×10^{-12}		11.0		mV p-p
EQUALIZER INPUT PATH					
Differential Input Sensitivity	15-inch FR-4, 100 Ω differential transmission line, adaptive EQ on				
8GFC[2]	JTSPAT, BER = 1×10^{-12}		115		mV p-p
OC-192	BER = 1×10^{-10}		184		mV p-p
INPUT—AC CHARACTERISTICS					
S11	At 7.5 GHz, differential return loss, see Figure 9		−12		dB
LOS DETECT					
Loss of Signal Detect			10		mV p-p
	Loss of signal minimum program value		5		mV p-p
	Loss of signal maximum program value		128		mV p-p
Hysteresis (Electrical)			5.7		dB
LOS Assert Time	AC-coupled[3]		135		µs
LOS Deassert Time	AC-coupled[3]		110		µs
LOSS OF LOCK (LOL) DETECT					
DCO Frequency Error for LOL Assert	With respect to nominal, data collected in lock to reference (LTR) mode		1000		ppm
DCO Frequency Error for LOL Deassert	With respect to nominal, data collected in LTR mode		250		ppm
LOL Assert Response Time	8.5 Gbps, JTSPAT		25		µs
	10 Gbps		18		µs
ACQUISITION TIME					
Lock to Data (LTD) Mode	OC192		0.5		ms
	11.3 Gbps		0.5		ms
	8.5 Gbps, JTSPAT		0.5		ms
Optional LTR Mode[4]			6.0		ms
DATA RATE READBACK ACCURACY					
Coarse Readback			±5		%
Fine Readback	In addition to reference clock accuracy		±100		ppm

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
POWER SUPPLY VOLTAGE					
VCC		1.14	1.2	1.26	V
VDD		2.97	3.3	3.63	V
VCC1		1.62	1.8	3.63	V
POWER SUPPLY CURRENT	Limiting amplifier mode, clock output enabled				
VCC	8GFC,[2] JTSPAT		319.1	359.5	mA
	OC-192		333	377.4	mA
VDD	8GFC,[2] JTSPAT		7.20	8.1	mA
	OC-192		7.21	8.59	mA
VCC1	8GFC,[2] JTSPAT		22.2	28.4	mA
	OC-192		35.1	47.4	mA
TOTAL POWER DISSIPATION					
Clock Output Enabled	Limiting amplifier mode, 8.5 Gbps		446.6		mW
	Limiting amplifier mode, 9.953 Gbps		486.5		mW
Clock Output Disabled	Equalizer mode, 8.5 Gbps		352		mW
	Equalizer mode, 11.3 Gbps		430		mW
OPERATING TEMPERATURE RANGE		−40		+85	°C

[1] See Figure 33.
[2] Fibre Channel Physical Interface 4 standard, FC-PI-4, Rev 8.00, May 21, 2008.
[3] When ac-coupled, the LOS assert and deassert times are dominated by the RC time constant of the ac coupling capacitor and the 100 Ω differential input termination of the ADN2917 input stage.
[4] This typical acquisition specification applies to all selectable reference clock frequencies in the range of 11.05 MHz to 176.8 MHz.

JITTER SPECIFICATIONS

$T_A = T_{MIN}$ to T_{MAX}, VCC = VCC_{MIN} to VCC_{MAX}, VCC1 = $VCC1_{MIN}$ to $VCC1_{MAX}$, VDD = VDD_{MIN} to VDD_{MAX}, VEE = 0 V, input data pattern: PRBS $2^{23} - 1$, ac-coupled to 100 Ω differential termination load, I^2C register default settings, unless otherwise noted.

Table 2.

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
PHASE-LOCKED LOOP CHARACTERISTICS					
Jitter Transfer Bandwidth (BW)[1]					
OC-192	TRANBW[2:0] = 3		1064	1650	kHz
	OTN mode,[2] TRANBW[2:0] = 1		294	529	kHz
8GFC[3]			1242	1676	kHz
Jitter Peaking					
OC-192	20 kHz to 80 MHz		0.014	0.024	dB
8GFC[3]	20 kHz to 80 MHz		0.004	0.021	dB
Jitter Generation					
OC-192	Unfiltered		0.0045	0.0067	UI rms
	Unfiltered		0.076		UI p-p
8GFC[3]	Unfiltered		0.005		UI rms
	Unfiltered		0.044		UI p-p
Jitter Tolerance	TRANBW[2:0] = 4 (default)				
OC-192	2000 Hz		4255		UI p-p
	20 kHz		106		UI p-p
	400 kHz		3.78		UI p-p
	4 MHz	0.36	0.50		UI p-p
	80 MHz	0.28	0.43		UI p-p

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
8GFC,[3] JTSPAT					
Sinusoidal Jitter at 340 kHz			6.7		UI p-p
Sinusoidal Jitter at 5.098 MHz			0.53		UI p-p
Sinusoidal Jitter at 80 MHz			0.59		UI p-p
Rx Jitter Tracking Test[4]	Voltage modulation amplitude (VMA) = 170 mV p-p at 100 MHz, 425 mV p-p at 100 MHz, 170 mV p-p at 2.5 GHz, and 425 mV p-p at 2.5 GHz excitation frequency[5]				
510 kHz, 1 UI		10^{-12}	$<10^{-12}$		BER
100 kHz, 5 UI		10^{-12}	$<10^{-12}$		BER

[1] Jitter transfer bandwidth is programmable by adjusting TRANBW[2:0] in the DPLLA register (Register 0x10).
[2] Set TRANBW[2:0] (Bits[D2:D0] in Register 0x10) = 1 to enter OTN mode. OTN is the optical transport network as defined in ITU G.709.
[3] Fibre Channel Physical Interface 4 standard, FC-PI-4, Rev 8.00, May 21, 2008.
[4] Conditions of FC-PI-4, Rev 8.00, Table 27, 800-DF-EL-S apply.
[5] Must have zero errors during the tests for an interval of time that is $\leq 10^{-12}$ BER to pass the tests.

OUTPUT AND TIMING SPECIFICATIONS

$T_A = T_{MIN}$ to T_{MAX}, VCC = VCC_{MIN} to VCC_{MAX}, VCC1 = $VCC1_{MIN}$ to $VCC1_{MAX}$, VDD = VDD_{MIN} to VDD_{MAX}, VEE = 0 V, input data pattern: PRBS $2^{23} - 1$, ac-coupled to 100 Ω differential termination load, I^2C register default settings, unless otherwise noted.

Table 3.

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
CML OUTPUT CHARACTERISTICS					
Data Differential Output Swing	OC-192, DATA_SWING[3:0] (Bits[D7:D4] in Register 0x1F) setting = 0xC (default)	535	600	672	mV p-p
	OC-192, DATA_SWING[3:0] setting = 0xF (maximum)	668	724	771	mV p-p
	OC-192, DATA_SWING[3:0] setting = 0x4 (minimum)	189	219	252	mV p-p
Clock Differential Output Swing	OC-192, CLOCK_SWING[3:0] (Bits[D3:D0] in Register 0x1F) setting = 0xC (default)	406	508	570	mV p-p
	OC-192, CLOCK_SWING[3:0] setting = 0xF (maximum)	448	583	659	mV p-p
	OC-192, CLOCK_SWING[3:0] setting = 0x4 (minimum)	162	217	249	mV p-p
Data Differential Output Swing	8GFC, DATA_SWING[3:0] setting = 0xC (default)	540	600	666	mV p-p
	8GFC, DATA_SWING[3:0] setting = 0xF (maximum)	662	725	778	mV p-p
	8GFC, DATA_SWING[3:0] setting = 0x4 (minimum	190	214	245	mV p-p
Clock Differential Output Swing	8GFC, CLOCK_SWING[3:0] setting = 0xC (default)	426	518	588	mV p-p
	8GFC, CLOCK_SWING[3:0] setting = 0xF (maximum)	489	603	680	mV p-p
	8GFC, CLOCK_SWING[3:0] setting = 0x4 (minimum)	166	213	245	mV p-p
Output High Voltage	V_{OH}, dc-coupled	VCC – 0.05	VCC – 0.025	VCC	V
Output Low Voltage	V_{OL}, dc-coupled	VCC – 0.36	VCC – 0.325	VCC – 0.29	V
CML OUTPUT TIMING CHARACTERISTICS					
Rise Time	20% to 80%, at OC-192, DATOUTN/DATOUTP	17.4	32.6	46.5	ps
	20% to 80%, at OC-192, CLKOUTN/CLKOUTP	22.2	28.3	33.1	ps
	20% to 80%, at 8GFC,[1] DATOUTN/DATOUTP	20.4	33.1	44	ps
	20% to 80%, at 8GFC,[1] CLKOUTN/CLKOUTP	23.1	29.7	35.8	ps
Fall Time	80% to 20%, at OC-192, DATOUTN/DATOUTP	17.5	33	49.1	ps
	80% to 20%, at OC-192, CLKOUTN/CLKOUTP	23.9	29.2	33.7	ps
	80% to 20%, at 8GFC,[1] DATOUTN/DATOUTP	23	34.2	46.8	ps
	80% to 20%, at 8GFC,[1] CLKOUTN/CLKOUTP	25	31.3	37.1	ps
Setup Time, Full Rate Clock	t_S (see Figure 2)		0.5		UI
Hold Time, Full Rate Clock	t_H (see Figure 2)		0.5		UI
Setup Time, DDR Clock	t_S (see Figure 3)		0.5		UI
Hold Time, DDR clock	t_H (see Figure 3)		0.5		UI

Parameter	Test Conditions/Comments	Min	Typ	Max	Unit
I²C INTERFACE DC CHARACTERISTICS	LVTTL				
Input High Voltage	V_{IH}	2.0			V
Input Low Voltage	V_{IL}			0.8	V
Input Current	V_{IN} = 0.1 × VDD or V_{IN} = 0.9 × VDD	−10.0		+10.0	µA
Output Low Voltage	V_{OL}, I_{OL} = 3.0 mA			0.4	V
I²C INTERFACE TIMING	See Figure 17				
SCK Clock Frequency				400	kHz
SCK Pulse Width High	t_{HIGH}	600			ns
SCK Pulse Width Low	t_{LOW}	1300			ns
Start Condition Hold Time	$t_{HD;STA}$	600			ns
Start Condition Setup Time	$t_{SU;STA}$	600			ns
Data Setup Time	$t_{SU;DAT}$	100			ns
Data Hold Time	$t_{HD;DAT}$	300			ns
SCK/SDA Rise/Fall Time[2]	t_R/t_F	20 + 0.1 C_b		300	ns
Stop Condition Setup Time	$t_{SU;STO}$	600			ns
Bus Free Time Between Stop and Start Conditions	t_{BUF}	1300			ns
LVTTL DC INPUT CHARACTERISITICS (I²C_ADDR)					
Input Voltage					
High	V_{IH}	2.0			V
Low	V_{IL}			0.8	V
Input Current					
High	I_{IH}, V_{IN} = 2.4 V			+5	µA
Low	I_{IL}, V_{IN} = 0.4 V	−5			µA
LVTTL DC OUTPUT CHARACTERISITICS (LOS/LOL)					
Output Voltage					
High	V_{OH}, I_{OH} = 2.0 mA	2.4			V
Low	V_{OL}, I_{OL} = −2.0 mA			0.4	V
REFERENCE CLOCK CHARACTERISTICS	Optional LTR mode				
Input Compliance Voltage (Single-Ended)	V_{CM} (no input offset, no input current), see Figure 25, ac-coupled input	0.55		1.0	V
Minimum Input Drive	See Figure 25, ac-coupled, differential input		100		mV p-p diff
Reference Frequency		11.05		176.8	MHz
Required Accuracy[3]	AC-coupled, differential input		100		ppm

[1] Fibre Channel Physical Interface 4 standard, FC-PI-4, Rev 8.00, May 21, 2008.
[2] C_b is the total capacitance of one bus line in picofarads (pF). If mixed with high speed (HS) mode devices, faster rise/fall times are allowed (refer to the Philips I²C Bus Specification, Version 2.1).
[3] Required accuracy in dc-coupled mode is guaranteed by design as long as the clock common-mode voltage output matches the reference clock common-mode voltage range.

TIMING DIAGRAMS

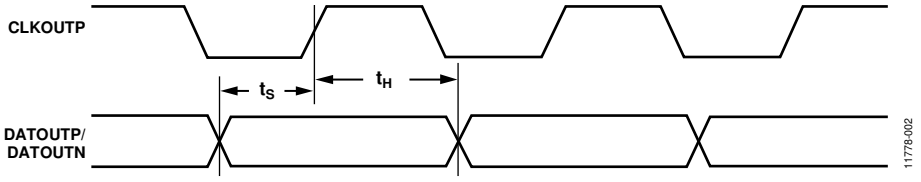

Figure 2. Data to Clock Timing (Full Rate Clock Mode)

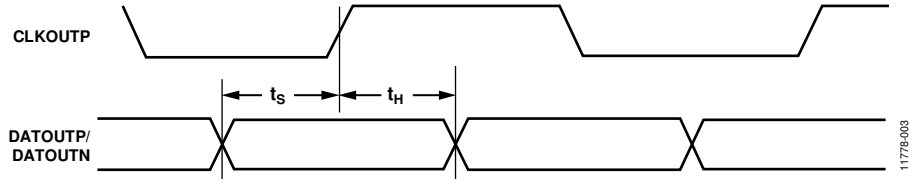

Figure 3. Data to Clock Timing (Half Rate Clock/DDR Mode)

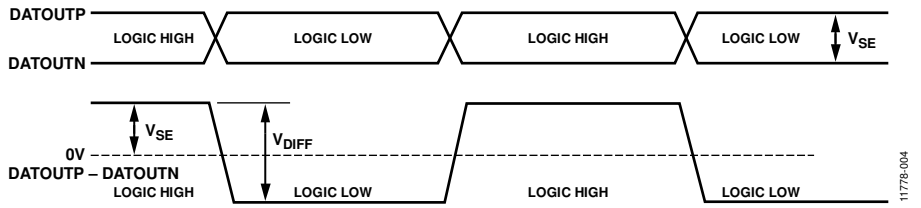

Figure 4. Single-Ended vs. Differential Output Amplitude Relationship

ABSOLUTE MAXIMUM RATINGS

Table 4.

Parameter	Rating
Supply Voltage (VCC = 1.2 V)	1.26 V
Supply Voltage (VDD and VCC1 = 3.3 V)	3.63 V
Maximum Input Voltage (REFCLKP/REFCLKN, NIN/PIN)	1.26 V
Minimum Input Voltage (REFCLKP/REFCLKN, NIN/PIN)	V_{EE} – 0.4 V
Maximum Input Voltage (SDA, SCK, I²C_ADDR)	3.63 V
Minimum Input Voltage (SDA, SCK, I²C_ADDR)	V_{EE} – 0.4 V
Maximum Junction Temperature	125°C
Storage Temperature Range	−65°C to +150°C
Lead Temperature (Soldering, 10 sec)	300°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL CHARACTERISTICS

Thermal Resistance

Thermal resistance is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages, for a 4-layer board with the exposed paddle soldered to VEE.

Table 5. Thermal Resistance

Package Type	θ_{JA}[1]	θ_{JB}[2]	θ_{JC}[3]	Unit
24-Lead LFCSP	45	5	11	°C/W

[1] Junction to ambient.
[2] Junction to base.
[3] Junction to case.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

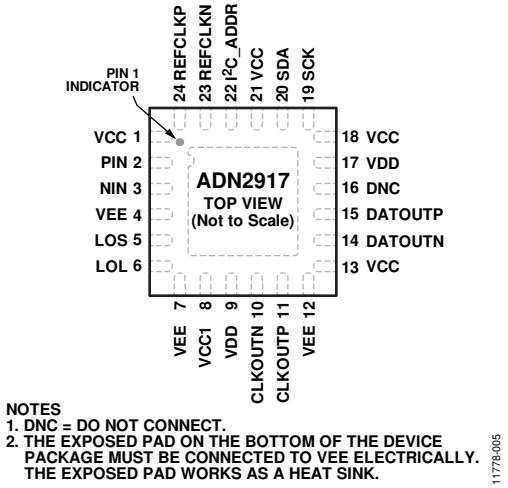

Figure 5. Pin Configuration

Table 6. Pin Function Descriptions

Pin No.	Mnemonic	Type[1]	Description
1	VCC	P	1.2 V Supply for Limiting Amplifier.
2	PIN	AI	Positive Differential Data Input (CML).
3	NIN	AI	Negative Differential Data Input (CML).
4	VEE	P	Ground for Limiting Amplifier.
5	LOS	DO	Loss of Signal Output (Active High).
6	LOL	DO	Loss of Lock Output (Active High).
7	VEE	P	Digital Control Oscillator (DCO) Ground.
8	VCC1	P	1.8 V to 3.3 V DCO Supply.
9	VDD	P	3.3 V High Supply.
10	CLKOUTN	DO	Negative Differential Recovered Clock Output (CML).
11	CLKOUTP	DO	Positive Differential Recovered Clock Output (CML).
12	VEE	P	Ground for CML Output Drivers.
13	VCC	P	1.2 V Supply for CML Output Drivers.
14	DATOUTN	DO	Negative Differential Retimed Data Output (CML).
15	DATOUTP	DO	Positive Differential Retimed Data Output (CML).
16	DNC	DI	Do Not Connect. Tie off to ground. Leave this pin floating.
17	VDD	P	3.3 V High Supply.
18	VCC	P	1.2 V Core Digital Supply.
19	SCK	DI	Clock for I^2C.
20	SDA	DIO	Bidirectional Data for I^2C.
21	VCC	P	1.2 V Core Supply.
22	I^2C_ADDR	DI	I^2C Address. Sets the device I^2C address = 0x80 when I^2C_ADDR = 0, and the device I^2C address = 0x82 when I^2C_ADDR = 1.
23	REFCLKN	DI	Negative Reference Clock Input (Optional).
24	REFCLKP	DI	Positive Reference Clock Input (Optional).
	EPAD	P	Exposed Pad (VEE). The exposed pad on the bottom of the device package must be connected to VEE electrically. The exposed pad works as a heat sink.

[1] P is power, AI is analog input, DI is digital input, DO is digital output, and DIO is digital input/output.

TYPICAL PERFORMANCE CHARACTERISTICS

T_A = 25°C, VCC = 1.2 V, VCC1 = 1.8 V, VDD = 3.3 V, VEE = 0 V, input data pattern: PRBS $2^{15} - 1$, ac-coupled inputs and outputs, unless otherwise noted.

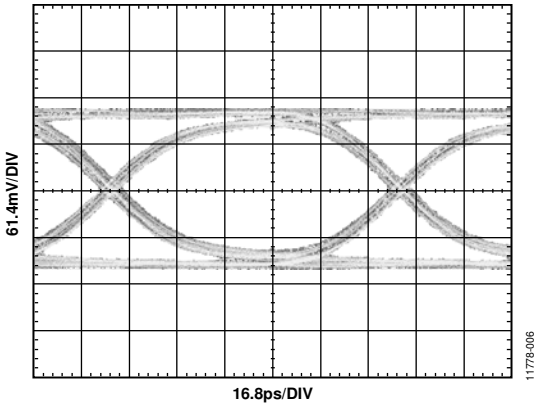

Figure 6. Output Eye Diagram at OC-192

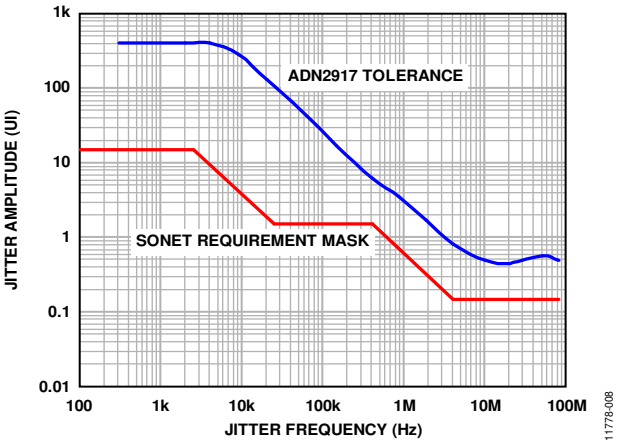

Figure 8. Jitter Tolerance: OC-192

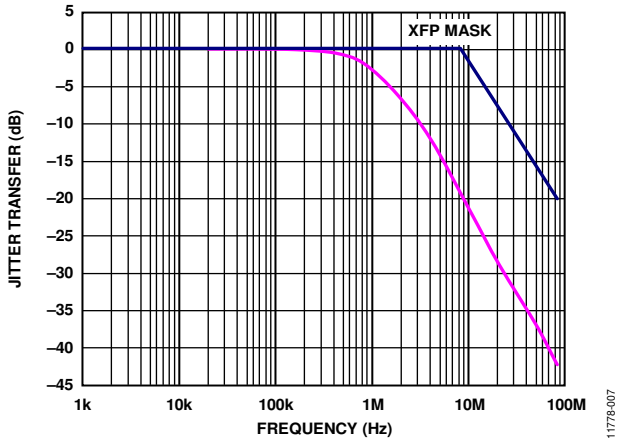

Figure 7. Jitter Transfer: OC-192, TRANBW[2:0] (Bits[D2:D0] in Register 0x10) = 3

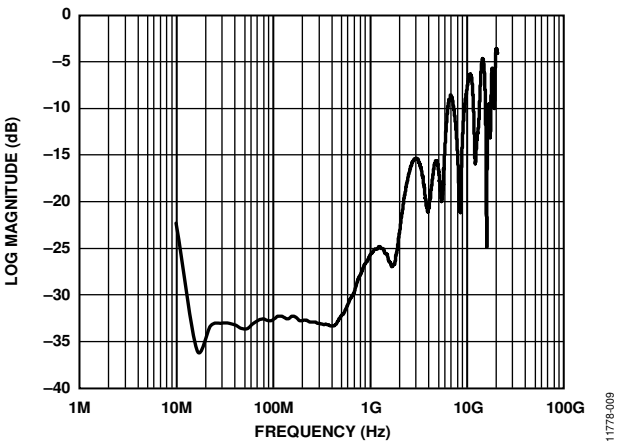

Figure 9. Typical S11 Spectrum Performance

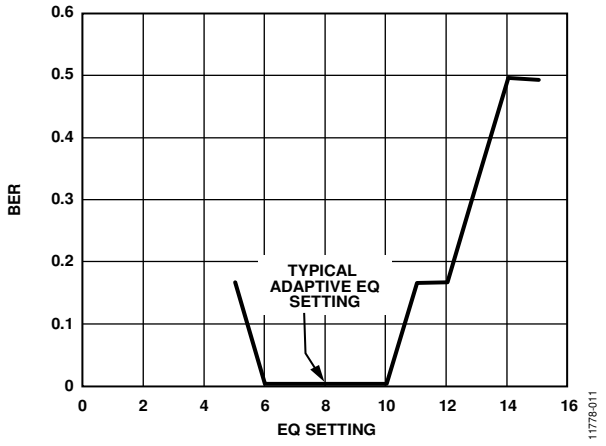

Figure 10. BER in Equalizer Mode vs. EQ Compensation at OC-192 (Measured with an OC-192 Signal of 400 mV p-p diff, on 15 Inch FR4 Traces, with Variant EQ Compensation, Including Adaptive EQ)

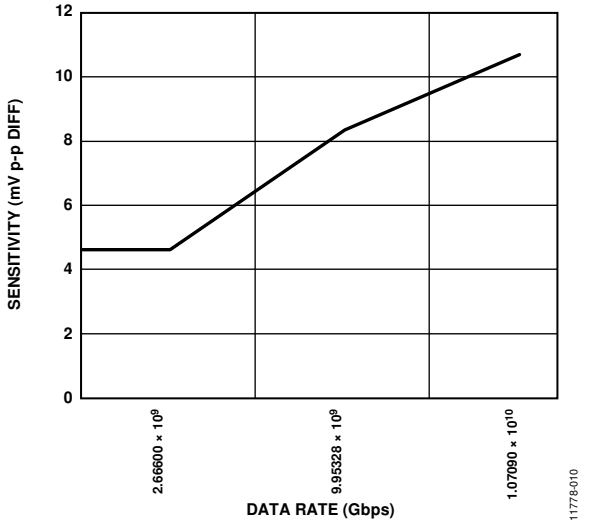

Figure 11. Sensitivities of SONET/SDH Data Rates (BER = 10^{-10})

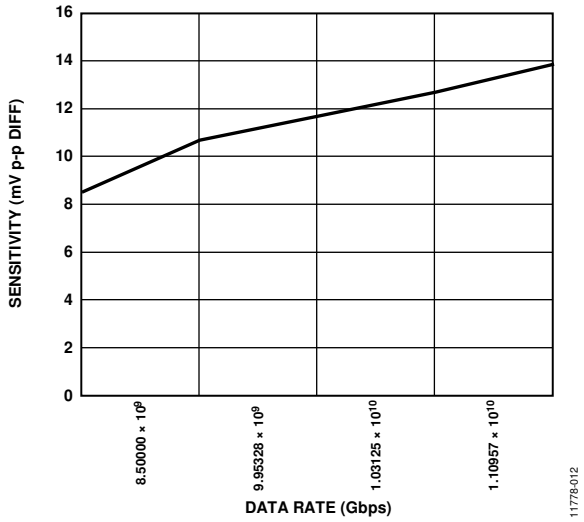

Figure 12. Sensitivities of Non SONET/SDH Data Rates (BER = 10^{-12})

I²C INTERFACE TIMING AND INTERNAL REGISTER DESCRIPTIONS

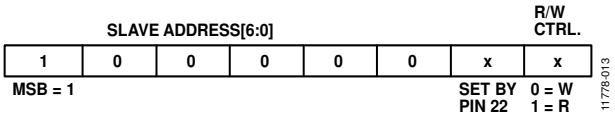

Figure 13. Slave Address Configuration

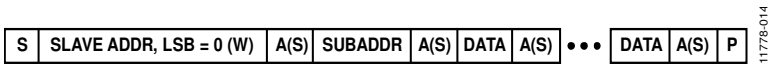

Figure 14. I²C Write Data Transfer

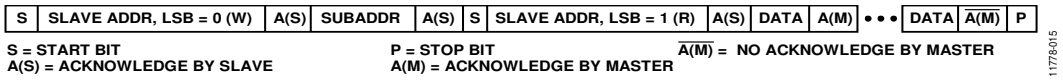

Figure 15. I²C Read Data Transfer

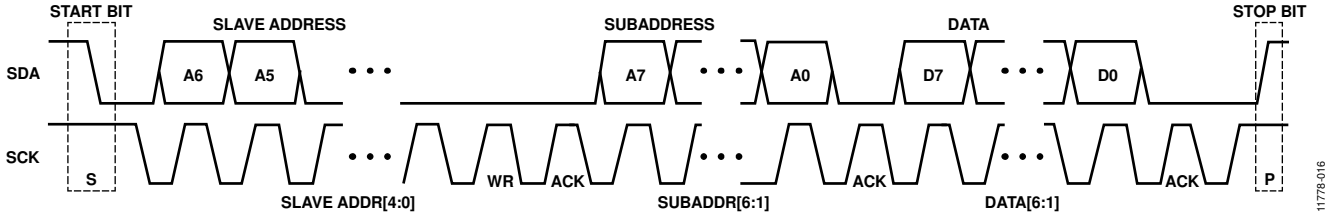

Figure 16. I²C Data Transfer Timing Diagram

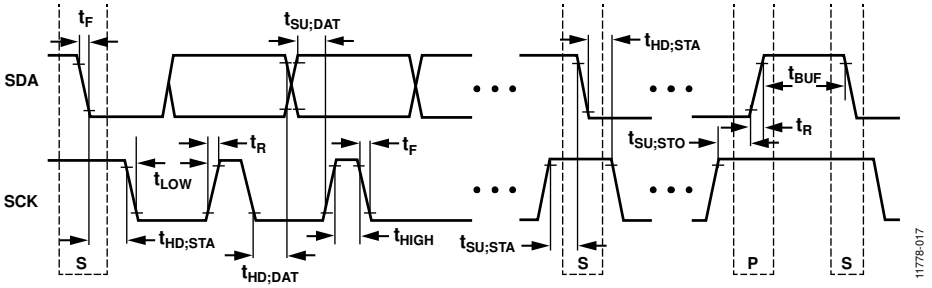

Figure 17. I²C Interface Timing Diagram

REGISTER MAP

Writing to register bits other than those clearly labeled is not recommended and may cause unintended results.

Table 7. Internal Register Map

Reg Name	R/W	Addr (Hex)[1]	Default (Hex)	D7	D6	D5	D4	D3	D2	D1	D0
Readback/Status											
FREQMEAS0	R	0x0	X	FREQ0[7:0] (RATE_FREQ[7:0])							
FREQMEAS1	R	0x1	X	FREQ1[7:0] (RATE_FREQ[15:8])							
FREQMEAS2	R	0x2	X	FREQ2[7:0] (RATE_FREQ[23:16])							
FREQ_RB1	R	0x4	X	VCOSEL[7:0]							
FREQ_RB2	R	0x5	X	X	FULLRATE	DIVRATE[3:0]				VCOSEL[9:8]	
STATUSA	R	0x6	X	X	X	LOS status	LOL status	LOS done	Static LOL	X	RATE_ MEAS_ COMP
General Control											
CTRLA	R/W	0x8	0x10	0	CDR_MODE[2:0]			0	Reset static LOL	RATE_ MEAS_ EN	RATE_MEAS_ RESET
CTRLB	R/W	0x9	0x00	SOFTWARE_ RESET	INIT_ FREQ_ ACQ	0	LOL_ CONFIG	LOS PDN	LOS polarity	0	0
CTRLC	R/W	0xA	0x04	0	0	0	0	0	REFCLK_ PDN	0	1
FLL Control											
LTR_MODE	R/W	0xF	0x00	0	LOL data	FREF_RANGE[1:0]		DATA_TO_REF_RATIO[3:0]			
D/PLL Control											
DPLLA	R/W	0x10	0x1C	0	0	0	EDGE_SEL[1:0]		TRANBW[2:0]		
DPLLD	R/W	0x13	0x06	0	0	0	0	0	ADAPTIVE_ SLICE_EN	DLL_SLEW[1:0]	
Phase	R/W	0x14	0x00	0	0	0	0	SAMPLE_PHASE[3:0]			
Slice	W	0x15	X	Extended slice	Slice[6:0]						
LA_EQ	R/W	0x16	0x08	RX_ TERM_ FLOAT	INPUT_SEL[1:0]		ADAPTIVE_ EQ_EN	EQ_BOOST[3:0]			
Slice Readback	R	0x73	X	SLICE_RB[7:0]							
Output Control											
OUTPUTA	R/W	0x1E	0x00	0	0	Data squelch	DATOUT_ DISABLE	CLKOUT_ DISABLE	0	DATA_ POLARITY	CLOCK_ POLARITY
OUTPUTB	R/W	0x1F	0xCC	DATA_SWING[3:0]				CLOCK_SWING[3:0]			
LOS Control											
LOS_DATA	R/W	0x36	0x00	LOS_DATA[7:0]							
LOS_THRESH	R/W	0x38	0x0A	LOS_THRESHOLD[7:0]							
LOS_CTRL	R/W	0x74	0x00	0	0	LOS_ WRITE	LOS_ ENABLE	LOS_ RESET	LOS_ADDRESS[2:0]		
PRBS Control											
PRBS Gen 1	R/W	0x39	0x00	0	0	DATA_ CID_ BIT	DATA_ CID_ EN	0	DATA_GEN_ EN	DATA_GEN_MODE[1:0]	
PRBS Gen 2	R/W	0x3A	0x00	DATA_CID_LENGTH[7:0]							
PRBS Gen 3	R/W	0x3B	0x00	PROG_DATA[7:0]							
PRBS Gen 4	R/W	0x3C	0x00	PROG_DATA[15:8]							
PRBS Gen 5	R/W	0x3D	0x00	PROG_DATA[23:16]							
PRBS Gen 6	R/W	0x3E	0x00	PROG_DATA[31:24]							
PRBS Rec 1	R/W	0x3F	0x00	0	0	0	0	DATA_ RECEIVER_ CLEAR	DATA_ RECEIVER_ ENABLE	DATA_RECEIVER_ MODE[1:0]	
PRBS Rec 2	R	0x40	0x00	PRBS_ERROR_COUNT[7:0]							
PRBS Rec 3	R	0x41	0x00	X	X	X	X	X	X	X	PRBS_ERROR

Reg Name	R/W	Addr (Hex)[1]	Default (Hex)	D7	D6	D5	D4	D3	D2	D1	D0
PRBS Rec 4	R	0x42	X	DATA_LOADED[7:0]							
PRBS Rec 5	R	0x43	X	DATA_LOADED[15:8]							
PRBS Rec 6	R	0x44	X	DATA_LOADED[23:16]							
PRBS Rec 7	R	0x45	X	DATA_LOADED[31:24]							
ID/Revision											
REV	R	0x48	0x54	REV[7:0]							
ID	R	0x49	0x15	ID[7:0]							
HI_CODE	R	0x20	0xFF	Reserved							
LO_CODE	R	0x21	0xA6	Reserved							

[1] X means don't care.

Table 8. Status Register, STATUSA (Address 0x6)

Bits	Bit Name	Bit Description
D5	LOS status	0 = no loss of signal 1 = loss of signal
D4	LOL status	0 = locked 1 = frequency acquisition mode
D3	LOS done	0 = LOS action not completed 1 = LOS action completed
D2	Static LOL	0 = no LOL event since last reset 1 = LOL event since last reset; clear by using the static LOL bit, CTRLA[D2]
D0	RATE_MEAS_COMP	Rate measurement complete 0 = frequency measurement incomplete 1 = frequency measurement complete; clear by using static the LOL bit, CTRLA[D0]

Table 9. Control Register, CTRLA (Address 0x8)

Bits	Bit Name	Bit Description
D7	0	Reserved to 0.
D6:D4	CDR_MODE[2:0]	CDR modes. 001 = lock to data (LTD). 011 = lock to reference (LTR). 000, 010 = reserved.
D3	0	Reserved to 0.
D2	Reset static LOL	Set to 1 to clear static LOL.
D1	RATE_MEAS_EN	Fine data rate measurement enable. Set to 1 to initiate a rate measurement.
D0	RATE_MEAS_RESET	Rate measurement reset. Set to 1 to clear a rate measurement.

Table 10. Control Register, CTRLB (Address 0x9)

Bits	Bit Name	Bit Description
D7	SOFTWARE_RESET	Software reset. Write a 1 followed by a 0 to reset the device.
D6	INIT_FREQ_ACQ	Initiate frequency acquisition. Write a 1 followed by a 0 to initiate a frequency acquisition (optional).
D5	0	Reserved; CDR is always enabled.
D4	LOL_CONFIG	LOL configuration. 0 = normal LOL. 1 = static LOL.
D3	LOS PDN	LOS power-down. 0 = normal LOS. 1 = LOS powered down.
D2	LOS polarity	LOS polarity. 0 = active high LOS pin. 1 = active low LOS pin.
D1:D0	0	Reserved to 0.

Table 11. Control Register, CTRLC (Address 0xA)

Bits	Bit Name	Bit Description
D7:D3	0	Reserved to 0.
D2	REFCLK_PDN	Reference clock power-down. Write a 0 to enable the reference clock.
D1	0	Reserved to 0.
D0	1	Reserved to 1.

Table 12. Lock to Reference Clock Mode Programming Register, LTR_MODE1 (Address 0xF)

Bits	Bit Name	Bit Description
D7	0	Reserved to 0
D6	LOL data	LOL data 0 = valid recovered clock vs. reference clock during tracking 1 = valid recovered clock vs. data during tracking
D5:D4	FREF_RANGE[1:0]	f_{REF} range 00 = 11.05 MHz to 22.1 MHz (default) 01 = 22.1 MHz to 44.2 MHz 10 = 44.2 MHz to 88.4 MHz 11 = 88.4 MHz to 176.8 MHz
D3:D0	DATA_TO_REF_RATIO[3:0]	Data to reference ratio 0000 = 1/2 0001 = 1 0010 = 2 $N = 2^{(n-1)}$ 1010 = 512

[1] Where DIV_f_{REF} is the divided down reference referred to the 11.05 MHz to 22.1 MHz band (see the Reference Clock (Optional) section).
$Data\ Rate/2^{(LTR\_MODE[3:0]-1)} = REFCLK/2^{LTR\_MODE[5:4]}$

Table 13. D/PLL Control Register, DPLLA (Address 0x10)

Bits	Bit Name	Bit Description
D7:D5	0	Reserved to 0.
D4:D3	EDGE_SEL[1:0]	Edge for phase detection. See the Edge Select section for further details. 00 = rising and falling edge data. 01 = rising edge data. 10 = falling edge data. 11 = rising and falling edge data.
D2:D0	TRANBW[2:0]	Transfer bandwidth. Scales transfer bandwidth. Default value is 4. See the Transfer Bandwidth section for further details. *Transfer BW = Default BW* × (*TRANBW[2:0]*/4)

Table 14. D/PLL Control Register, DPLLD (Address 0x13)

Bits	Bit Name	Bit Description
D7:D3	0	Reserved to 0.
D2	ADAPTIVE_SLICE_EN	Adaptive slice enable. 1 = enables automatic slice adjust.
D1:D0	DLL_SLEW[1:0]	DLL slew. Sets the BW of the DLL. See the DLL Slew section for further details.

Table 15. Phase Control Register, Phase (Address 0x14)

Bits	Bit Name	Bit Description
D7:D4	0	Reserved to 0.
D3:D0	SAMPLE_PHASE[3:0]	Adjust the phase of the sampling instant for data rates above 5.65 Gbps in steps of 1/32 UI. This register is in twos complement notation. See the Sample Phase Adjust section for further details.

Table 16. Slice Level Control Register, Slice (Address 0x15)

Bits	Bit Name	Bit Description
D7	Extended slice	Extended slice enable. 0 = normal slice mode. 1 = extended slice mode.
D6:D0	Slice[6:0]	Slice. Slice is a digital word that sets the input threshold. See the Slice Adjust section for further details. When Slice[6:0] = 0000000, the slice function is disabled.

Table 17. Input Stage Programming Register, LA_EQ (Address 0x16)

Bits	Bit Name	Bit Description
D7	RX_TERM_FLOAT	Rx termination float. 0 = termination common-mode driven. 1 = termination common-mode floated.
D6:D5	INPUT_SEL[1:0]	Input stage select. 00: limiting amplifier. 01: equalizer. 10: 0 dB buffer. 11: undefined.
D4	ADAPTIVE_EQ_EN	Enable adaptive EQ. 0 = manual EQ control. 1 = adaptive EQ enabled.
D3:D0	EQ_BOOST[3:0]	Equalizer gain. These bits set the EQ gain. See the Passive Equalizer section for further details.

Table 18. Output Control Register, OUTPUTA (Address 0x1E)

Bits	Bit Name	Bit Description
D7:D6	0	Reserved to 0
D5	Data squelch	Squelch 0 = normal data 1 = squelch data
D4	DATOUT_DISABLE	Data output disable 0 = data output enabled 1 = data output disabled
D3	CLKOUT_DISABLE	Clock output disable 0 = clock output enabled 1 = clock output disabled
D2	0	Reserved; double data rate is always enabled
D1	DATA_POLARITY	Data polarity 0 = normal data polarity 1 = flip data polarity
D0	CLOCK_POLARITY	Clock polarity 0 = normal clock polarity 1 = flip clock polarity

Table 19. Output Swing Register, OUTPUTB (Address 0x1F)

Bits	Bit Name	Bit Description
D7:D4	DATA_SWING[3:0]	Adjust data output amplitude. Step size is approximately 50 mV differential. Default register value is 0xC. Typical differential data output amplitudes are 0x1 = invalid. 0x2 = invalid. 0x3 = invalid. 0x4 = 200 mV. 0x5 = 250 mV. 0x6 = 300 mV. 0x7 = 345 mV. 0x8 = 390 mV. 0x9 = 440 mV. 0xA = 485 mV. 0xB = 530 mV. 0xC = 575 mV. 0xD = 610 mV. 0xE = 640 mV. 0xF = 655 mV.
D3:D0	CLOCK_SWING[3:0]	Adjust clock output amplitude. Step size is approximately 50 mV differential. Default register value is 0xC. Typical differential clock output amplitudes are 0x1 = invalid. 0x2 = invalid. 0x3 = invalid. 0x4 = 200 mV. 0x5 = 250 mV. 0x6 = 300 mV. 0x7 = 345 mV. 0x8 = 390 mV. 0x9 = 440 mV. 0xA = 485 mV. 0xB = 530 mV. 0xC = 575 mV. 0xD = 610 mV. 0xE = 640 mV. 0xF = 655 mV.

THEORY OF OPERATION

The ADN2917 implements a clock and data recovery for data rates between 8.5 Gbps and 11.3 Gbps. A front end is configurable to either amplify or equalize the nonreturn-to-zero (NRZ) input waveform to full-scale digital logic levels.

To process a high speed input data, the user can choose either a high gain limiting amplifier with better than 10 mV sensitivity, or a high-pass passive equalizer with up to 10 dB of boost at 5 GHz with 600 mV sensitivity.

An on-chip LOS detector works with the high sensitivity limiting amplifier. The default threshold for the LOS is the sensitivity of the device, with a maximum threshold level of 128 mV p-p. The limiting amplifier slice threshold can use a factory trim setting, a user-defined threshold set by the I²C, or an adjusted level for the best eye opening at the phase detector.

When the input signal is corrupted due to FR-4 or other impairments in the printed circuit board (PCB) traces, a passive equalizer can be one of the signal integrity options. The equalizer high frequency boost is configurable through the I²C registers, in place of the factory default settings. A user-enabled adaptation is included that automatically adjusts the equalizer to achieve the widest eye opening. The equalizer can be manually set for any data rate from 8.5 Gbps up to 11.3 Gbps.

When a signal is presented to the clock and data recovery (CDR), the ADN2917 is a delay-locked and phase-locked loop circuit for clock recovery and data retiming from an NRZ encoded data stream. Input data is sampled by a high speed clock. A digital downsampler accommodates data rates spanning three orders of magnitude. Downsampled data is applied to a binary phase detector.

The phase of the input data signal is tracked by two separate feedback loops. A high speed delay-locked loop path cascades a digital integrator with a digitally controlled phase shifter on the DCO clock to track the high frequency components of jitter. A separate phase control loop composed of a digital integrator and DCO tracks the low frequency components of jitter.

The initial frequency of the DCO is set by a third loop that compares the DCO frequency with the input data frequency. This third loop also sets the decimation ratio of the digital downsampler.

The delay-locked loop (DLL) and phase-locked loop (PLL) together track the phase of the input data. For example, when the clock lags the input data, the phase detector drives the DCO to a higher frequency and decreases the delay of the clock through the phase shifter; both of these actions serve to reduce the phase error between the clock and data. Because the loop filter is an integrator, the static phase error is driven to zero.

Another view of the circuit is that the phase shifter implements the zero required for frequency compensation of a second-order phase-locked loop, and this zero is placed in the feedback path and, thus, does not appear in the closed-loop transfer function. Because this circuit has no zero in the closed-loop transfer, jitter peaking is eliminated.

The delay-locked and phase-locked loops, together, simultaneously provide wideband jitter accommodation and narrow-band jitter filtering. The simplified block diagram in Figure 18 shows that Z(s)/X(s) is a second-order low-pass jitter transfer function that provides excellent filtering. The low frequency pole is formed by dividing the gain of the PLL by the gain of the DLL, where the upsampling and zero-order hold in the DLL has a gain approaching N at the transfer bandwidth of the loop. Note that the jitter transfer has no zero, unlike an ordinary second-order phase-locked loop. This means that the main PLL loop has no jitter peaking. This makes the circuit ideal for signal regenerator applications, where jitter peaking in a cascade of regenerators can contribute to hazardous jitter accumulation.

The error transfer, e(s)/X(s), has the same high-pass form as an ordinary phase-locked loop up to the slew rate limit of the DLL with a binary phase detector. This transfer function is free to be optimized to give excellent wideband jitter accommodation because the jitter transfer function, Z(s)/X(s), provides the narrow-band jitter filtering.

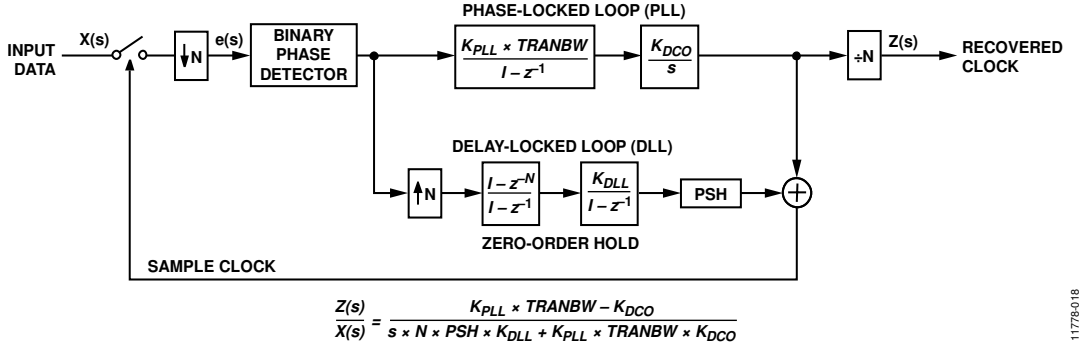

Figure 18. CDR Jitter Block Diagram

The delay-locked and phase-locked loops contribute to overall jitter accommodation. At low frequencies of input jitter on the data signal, the integrator in the loop filter provides high gain to track large jitter amplitudes with small phase error. In this case, the oscillator is frequency modulated and jitter is tracked as in an ordinary phase-locked loop. The amount of low frequency jitter that can be tracked is a function of the DCO tuning range. A wider tuning range gives larger accommodation of low frequency jitter. The internal loop control word remains small for small jitter frequency so that the phase shifter remains close to the center of the range and, thus, contributes little to the low frequency jitter accommodation.

At medium jitter frequencies, the gain and tuning range of the DCO are not large enough to track input jitter. In this case, the DCO control word becomes large and saturates. As a result, the DCO frequency dwells at an extreme of the tuning range. The size of the DCO tuning range, therefore, has only a small effect on the jitter accommodation. The delay-locked loop control range is now larger; therefore, the phase shifter takes on the burden of tracking the input jitter. An infinite range phase shifter is used on the clock. Consequently, the minimum range of timing mismatch between the clock at the data sampler and the retiming clock at the output is limited to 32 UI by the depth of the FIFO.

There are two ways to acquire the data rate. The default mode frequency locks to the input data, where a finite state machine extracts frequency measurements from the data to program the DCO and loop division ratio so that the sampling frequency matches the data rate to within 250 ppm. The PLL is enabled, driving this frequency difference to 0 ppm. The second mode is lock to reference, in which case the user provides a reference clock between 11.05 MHz and 176.8 MHz. Division ratios must be written to a serial port register.

FUNCTIONAL DESCRIPTION

FREQUENCY ACQUISITION

The ADN2917 acquires frequency from the data over a range of data frequencies from 8.5 Gbps to 11.3 Gbps. The lock detector circuit compares the frequency of the DCO and the frequency of the incoming data. When these frequencies differ by more than 1000 ppm, LOL is asserted and a new frequency acquisition cycle is initiated. The DCO frequency is reset to the bottom of the range, and the internal division rate is set to the lowest value of N = 1, which is the highest octave of data rates. The frequency detector then compares this sampling rate frequency to the data rate frequency and either increases N by a factor of 2 if the sampling rate frequency is found to be greater than the data rate frequency, or increases the DCO frequency if the data rate frequency is found to be greater than the data sampling rate. Initially, the DCO frequency is incremented in large steps to aid fast acquisition. As the DCO frequency approaches the data frequency, the step size is reduced until the DCO frequency is within 250 ppm of the data frequency, at which point LOL is deasserted.

When LOL is deasserted, the frequency-locked loop is turned off. The PLL or DLL pulls in the DCO frequency until the DCO frequency equals the data frequency.

LIMITING AMPLIFIER

The limiting amplifier has differential inputs (PIN and NIN) that are each internally terminated with 50 Ω to an on-chip voltage reference (V_{CM} = 0.95 V typically). The inputs must be ac-coupled. Input offset is factory trimmed to achieve better than 10 mV p-p typical sensitivity with minimal drift. The limiting amplifier can be driven differentially or single-ended. DC coupling of the limiting amplifier is not possible because the user must supply a common-mode voltage to exactly match the internal common-mode voltage; otherwise, the internal 50 Ω termination resistors absorb the difference in common-mode voltages.

Another reason the limiting amplifier cannot be dc-coupled is that the factory trimmed input offset becomes invalid. The offset is adjusted to zero by differential currents from the slice adjust digital-to-analog converted (DAC) (see Figure 1). With ac coupling, all of the current goes to the 50 Ω termination resistors on the ADN2917. However, with dc coupling, this current is shared with the external drive circuit, and calibration of the offset is lost. In addition, the slice adjust must have all the current from the slice adjust DAC go to the resistors; otherwise, the calibration is lost (see the Slice Adjust section).

SLICE ADJUST

The quantizer slicing level can be offset by ±100 mV in 1.6 mV steps or about ±15 mV in 0.24 mV steps to mitigate the effect of amplified spontaneous emission (ASE) noise or duty cycle distortion. Quantizer slice adjust level is set by the Slice[6:0] (Bits[D6:D0] in I²C Register 0x15).

Accurate control of the slice threshold requires the user to read back the factory trimmed offset, which is stored as a 7-bit number in the I²C slice readback register (Register 0x73). Use Table 20 to decode the measured offset of the part, where an LSB corresponds to 0.24 mV.

Table 20. Program Slice Level, Normal Slice Mode (Extended Slice = 0)

Slice[6:0]	Decimal Value	Offset
0000000	0	Slice function disabled
0000001	1	−15 mV
…	…	…
1000000	64	0 mV
…	…	…
1111111	127	+14.75 mV

The amount of offset required for manual slice adjust is determined by subtracting the offset of the device from the desired slice adjust level. Use Table 20 or Table 21 to determine the code word to be written to the I²C slice register.

An extended slice with coarser granularity for each LSB step is found in Table 21. Setting the extended slice bit (Bit 7) = 1 in Register 0x15 scales the full-scale range of the slice adjust by a factor of 6.

Table 21. Program Slice Level, Extended Slice Mode (Extended Slice = 1)

Slice[6:0]	Decimal Value	Offset
0000000	128	Slice function disabled
0000001	129	−100 mV
…	…	…
1000000	192	0 mV
…	…	…
1111111	255	+100 mV

When manual slice is desired, disable the dc offset loop, which drives duty cycle distortion on the data to 0. Adaptive slice is disabled by setting ADAPTIVE_SLICE_EN = 0 in the DPLLD register (Register 0x13).

EDGE SELECT

A binary or Alexander phase detector drives both the DLL and PLL loops at all division rates. Duty cycle distortion on the received data leads to a dead band in the phase detector transfer function if phase errors are measured on both rising and falling data transitions. This dead band leads to jitter generation of unknown spectral composition whose peak-to-peak amplitude is potentially large.

The recommended usage of the device when the dc offset loop is disabled computes phase errors exclusively on either the rising data edges with EDGE_SEL[1:0] (Bits[D4:D3] in Register 0x10) = 1 (decimal) or falling data edges with EDGE_SEL[1:0] (Bits[D4:D3] in Register 0x10) = 2.

The alignment of the clock to the rising data edges with EDGE_SEL[1:0] = 1 is represented by the top two curves in Figure 19. Duty cycle distortion with narrow 1s moves the significant sampling instance where data is sampled to the right of center. The alignment of the clock to the falling data edges with EDGE_SEL[1:0] = 2 is represented by the first and third curves in Figure 19. The significant sampling instance moves to the left of center. Sample phase adjust for rates above 5.65 Gbps can move the significant sampling instance to the center of the narrow 1 (or narrow 0) for best jitter tolerance.

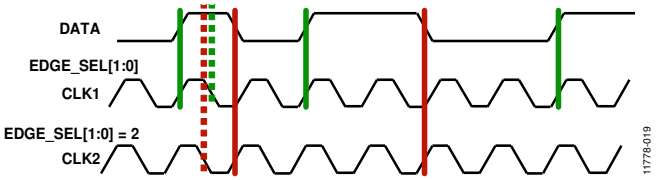

Figure 19. Phase Detector Timing

DLL Slew

Jitter tolerance beyond the transfer bandwidth of the CDR is determined by the slew rate of the delay-locked loop implementing a delta modulator on phase. Setting DLL_SLEW[1:0] (Bits[D1:D0] in Register 0x13) = 2, the default value, configures the DLL to track 0.75 UI p-p jitter at the highest frequency breakpoint in the SONET/SDH jitter tolerance mask. This frequency scales with the rate as f_{p5} = Rate (Hz)/2500 (for example, 4.0 MHz for OC-192). Peak-to-peak tracking in UI at f_{p4} obeys the expression (1 + DLL_SLEW)/4 UI p-p.

In some applications, full SONET/SDH jitter tolerance is not needed. In this case, DLL_SLEW[1:0] (Bits[D1:D0] in Register 0x13) can be set to 0, giving lower jitter generation on the recovered clock and better high frequency jitter tolerance.

Sample Phase Adjust

The phase of the sampling instant can be adjusted over the I²C when operating at data rates of 5.65 Gbps or higher by writing to the SAMPLE_PHASE[3:0] bits (Bits[D3:D0] in Register 0x14). This feature allows the user to adjust the sampling instant with the intent of improving the BER and jitter tolerance.

Although the default sampling instant chosen by the CDR is sufficient in most applications, when dealing with some degraded input signals, the BER and jitter tolerance performance can be improved by manually adjusting the phase.

There is a total adjustment range of 0.5 UI, with 0.25 UI in each direction, in increments of 1/32 UI. SAMPLE_PHASE[3:0] (Bits[D3:D0] in Register 0x14) is a twos complement number, and the relationship between data and the sampling clock is shown in Figure 20.

Transfer Bandwidth

The transfer bandwidth can be adjusted over the I²C by writing to TRANBW[2:0] (Bits[D2:D0] in Register 0x10). The default value is 4. When set to values below 4, the transfer bandwidth is reduced, and when set to values above 4, the transfer bandwidth is increased. The resulting transfer bandwidth is based on the following formula:

$$Transfer\ BW = (Default\ Transfer\ BW) \times \left(\frac{TRANBW[2:0]}{4}\right)$$

For example, at OC-192, the default transfer bandwidth is 1.4 GHz. The resulting transfer bandwidth when TRANBW[2:0] is changed is reflected in Table 22.

Table 22. Transfer Bandwidth Adjustments

TRANBW[2:0] Value	Transfer BW (kHz)
1	350
2	700
3	1050
4	1400 (default)
5	1750
6	2100
7	2450

Reducing the transfer bandwidth is commonly used in OTN applications. Never set TRANBW[2:0] = 0, because this makes the CDR open-loop. Also, note that setting TRANBW[2:0] above 4 may cause a slight increase in jitter generation and potential jitter peaking.

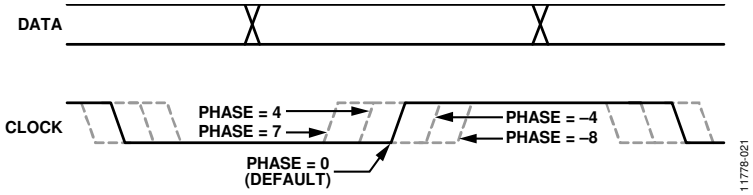

Figure 20. Data vs. Sampling Clock LOS Detector Hysteresis

LOSS OF SIGNAL DETECTOR

The receiver front-end LOS detector circuit detects when the input signal level falls below a user adjustable threshold.

There is typically 6 dB of electrical hysteresis on the LOS detector to prevent chatter on the LOS pin. This means that, if the input level drops below the programmed LOS threshold, causing the LOS pin to assert, the LOS pin is not deasserted until the input level has increased to 6 dB (2×) above the LOS threshold (see Figure 21).

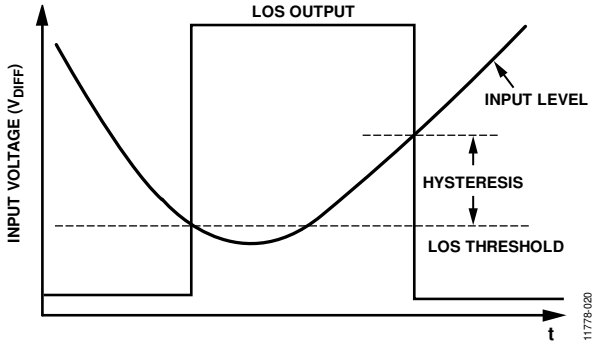

Figure 21. LOS Detector Hysteresis

The LOS detector and the slice level adjust can be used simultaneously on the ADN2917. Therefore, any offset added to the input signal by the slice adjust bits (Bits[D6:D0] in Register 0x15) does not affect the LOS detector measurement of the absolute input level.

LOS Power-Down

The LOS, by default, is enabled and consumes power. The LOS is placed in a low power mode by setting LOS PDN (Bit D3 in Register 0x9) = 1.

LOS Threshold

The LOS threshold has a range between 0 mV and 128 mV and is set by writing the number of millivolts (mV) to the LOS_DATA register (Register 0x36), followed by toggling the LOS_ENABLE bit (Bit D4 in Register 0x74) while LOS_ADDRESS is set to 1. The following is a procedure for writing the LOS threshold:

1. Write 0x21 to LOS_CTRL (Register 0x74).
2. Write the desired threshold in millivolts to LOS_DATA (Register 0x36).
3. Write 0x31 to LOS_CTRL (Register 0x74).
4. Write 0x21 to LOS_CTRL (Register 0x74).

The LOS threshold can be set to a value between 0 mV and 63 mV in 1 mV steps and 64 mV to 128 mV in 2 mV steps. In the lower range, all of the bits are active, giving 1 mV/LSB resolution, where Bit D0 is the LSB.

However, in the upper range, Bit D0 is disabled (that is, D0 = 0), making Bit D1 the new LSB and resulting in 2 mV/LSB resolution.

I^2C Register LOS_CTRL (Register 0x74) contains the necessary address and write enable bits to program this LOS threshold.

Signal Strength Measurement

The LOS measures and digitizes the peak-to-peak amplitude of the received signal. A single shot measurement is taken by writing the following sequence of bytes to LOS_CTRL (Register 0x74). at I^2C Address 0x74: 0x7, 0x17, 0x7. Upon LOS_ENABLE (Bit D4 in Register 0x74) going low, the peak-to-peak amplitude in millivolts is loaded into LOS_DATA (Register 0x36). The contents of LOS_DATA change only when LOS_ENABLE (Bit D4 in Register 0x74) is toggled low to high to low while pointing to LOS_ADDRESS[2:0] (Bits[D2:D0] in Register 0x74) = 7.

PASSIVE EQUALIZER

A passive equalizer (EQ) is available at the input to equalize large signals that have undergone distortion due to PCB traces, vias, and connectors. The adaptive equalizer of the ADN2917 is a factory set default function. If needed, the EQ can be manually set.

The equalizer can be manually set through the LA_EQ Register (Register 0x16). An adaptive loop is also available that optimizes the EQ setting based on characteristics of the received eye at the phase detector. If the channel is known in advance, set the EQ setting manually to obtain the best performance; however, the adaptive EQ finds the best setting in most cases.

Table 23 indicates a typical EQ setting for several trace lengths. The values in Table 23 are based on measurements taken on a test board with simple FR-4 traces. Table 24 lists the typical maximum reach in inches of FR-4 of the EQ at several data rates. If a real channel includes lossy connectors or vias, the FR-4 reach length is shorter. For any real-world system, it is highly recommended to test several EQ settings with the real channel to ensure best signal integrity.

Table 23. EQ Settings vs. Trace Length on FR-4

Trace Length (Inches)	Typical EQ Setting
6	10
10	12
15	14
20 to 30	15

Table 24. Typical EQ Reach on FR-4 vs. Maximum Data Rates Supported

Maximum Data Rate (Gbps)	Typical EQ Reach on FR-4 (Inches)
4	30
8	20
10	15
11	10

0 dB EQ

The 0 dB EQ path connects the input signal directly to the digital logic inside the ADN2917. This is useful at lower data rates where the signal is large (therefore, the limiting amplifier is not needed, and power can be saved by deselecting the limiting amplifier) and unimpaired (therefore, the equalizer is not needed). The signal swing of the internal digital circuit is 600 mV p-p differential, the minimum signal amplitude that must be provided as the input in 0 dB EQ mode.

In 0 dB EQ mode, the internal 50 Ω termination resistors can be configured in one of two ways, either floated or tied to V_{CC} = 1.2 V (see Figure 26 and Table 28). By setting the RX_TERM_FLOAT (Bit D7 in Register 0x16) to 1, these 50 Ω termination resistors are floated internal to the ADN2917 (see Figure 26 and Figure 29). By setting the RX_TERM_FLOAT bit to 0, these 50 Ω termination resistors are connected to V_{CC} = 1.2 V (see Figure 26 and Figure 30). In both of these termination cases, the user must ensure a valid common-mode voltage on the input.

In the case where the termination is floated, the two 50 Ω resistors are purely a differential termination. The input must conform to the range of signals shown in Figure 32 and Figure 33.

In the case of termination to a 1.2 V V_{CC} power supply (see Figure 30 and Figure 31), the common-mode voltage is created by joint enterprise between the driver circuit and the 50 Ω resistors on the ADN2917. For example, the driver can be an open-drain switched current (see Figure 30), and the 50 Ω resistors return this current to V_{CC}. In Figure 30, the common-mode voltage is created by both the current and the resistors. In this case, ensure that the current is a minimum of 6 mA, which gives a single-ended swing of 300 mV or a differential swing of 600 mV p-p differential, with V_{CM} = 1.05 V (see Figure 32). The maximum current is 10 mA, which gives a single-ended 500 mV swing and differential 1.0 V p-p, with V_{CM} = 0.95 V (see Figure 33).

Another possibility is to have the switched current driver back terminated, as shown in Figure 31, and the two V_{CC} supplies having the same potential. In this example, the current is returned to V_{CC} by two 50 Ω resistors in parallel, or 25 Ω, so that the minimum current is 12 mA and the maximum current is 20 mA.

LOCK DETECTOR OPERATION

The lock detector on the ADN2917 has three modes of operation: normal mode, LTR mode, and static LOL mode.

Normal Mode

In normal mode, the ADN2917 is a continuous rate CDR that locks onto any data rate from 8.5 Gbps to 11.3 Gbps without the use of a reference clock as an acquisition aid. In this mode, the lock detector monitors the frequency difference between the DCO and the input data frequency, and deasserts the loss of lock signal, which appears on LOL, Pin 6, when the DCO is within 250 ppm of the data frequency. This enables the digital PLL (D/PLL), which pulls the DCO frequency in the remaining amount and acquires phase lock. When locked, if the input frequency error exceeds 1000 ppm (0.1%), the loss of lock signal is reasserted and control returns to the frequency loop, which begins a new frequency acquisition. The LOL pin remains asserted until the DCO locks onto a valid input data stream to within 250 ppm frequency error. This hysteresis is shown in Figure 22.

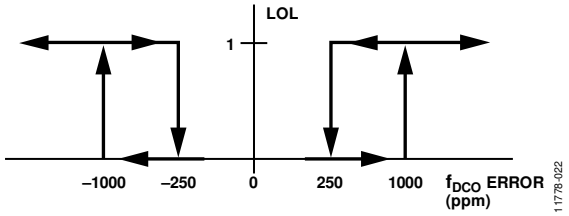

Figure 22. Transfer Function of LOL

Look to Reference (LTR) Mode

In LTR mode, a reference clock is used as an acquisition aid to lock the ADN2917 DCO. Lock to reference mode is enabled by setting CDR_MODE[2:0] (Bits[D6:D4] in Register 0x8) to 3. The user must also write to FREF_RANGE[1:0] (Bits[D5:D4] in Register 0xF) and DATA_TO_REF_RATIO[3:0] (Bits[D3:D0] in Register 0xF) in the LTR_MODE register (Register 0xF) to set the reference frequency range and the divide ratio of the data rate with respect to the reference frequency. Finally, the reference clock power-down to the reference clock buffer must be deasserted by writing a 0 to I^2C the REFCLK_PDN bit (Bit D2 in Register 0xA). To maintain fastest acquisition, keep Bit D0 in CTRLC (Register 0xA) set to 1.

For more details, see the Reference Clock (Optional) section. In this mode, the lock detector monitors the difference in frequency between the divided down DCO and the divided down reference clock. The loss of lock signal, which appears on LOL (Pin 6), is deasserted when the DCO is within 250 ppm of the desired frequency. This enables the D/PLL, which pulls in the DCO frequency the remaining amount with respect to the input data and acquires phase lock. When locked, if the frequency error exceeds 1000 ppm (0.1%), the loss of lock signal is reasserted and control returns to the frequency loop, which reacquires with respect to the reference clock. The LOL pin remains asserted until the DCO frequency is within 250 ppm of the desired frequency. This hysteresis is shown in Figure 22.

Static LOL Mode

The ADN2917 implements a static LOL feature that indicates if a loss of lock condition has ever occurred and remains asserted, even if the ADN2917 regains lock, until the static LOL bit (Bit D2 in Register 0x6) is manually reset. If there is ever an occurrence of a loss of lock condition, this bit is internally asserted to logic high. The static LOL bit remains high even after the ADN2917 has reacquired lock to a new data rate. This bit can be reset by writing a 1, followed by 0, to the reset static LOL bit (Bit D2 in Register 0x8). When reset, the static LOL bit (Bit D2 in Register 0x6) remains deasserted until another loss of lock condition occurs.

Writing a 1 to the LOL_CONFIG bit (Bit D4 in Register 0x9) causes the LOL pin, Pin 6, to become a static LOL indicator. In this mode, the LOL pin mirrors the contents of the static LOL bit (Bit D2 in Register 0x6) and has the functionality described previously. The LOL_CONFIG bit (Bit D4 of Register 0x9) defaults to 0. In this mode, the LOL pin operates in the normal operating mode; that is, it is asserted only when the ADN2917 is in acquisition mode and deasserts when the ADN2917 has reacquired lock.

OUTPUT DISABLE AND SQUELCH

The ADN2917 has two types of output disable/squelch. The DATOUTP/DATOUTN and CLKOUTP/CLKOUTN outputs can be disabled by setting DATOUT_DISABLE (Bit D4 in Register 0x1E) and CLKOUT_DISABLE (Bit D3 in Register 0x1E) high, respectively. When an output is disabled, it is fully powered down, saving approximately 30 mW per output. Disabling DATOUTP/DATOUTN also disables the CLKOUTP/CLKOUTN output, saving a total of about 60 mW of power.

If it is desired to gate the data output while leaving the clock on, the output data can be squelched by setting the data squelch bit (Bit D5 in Register 0x1E) high. In this mode, the data driver is left powered, but the data itself is forced to be always 0 (or 1), depending on the setting of the DATA_POLARITY bit (Bit D1 in Register 0x1E).

I²C INTERFACE

The ADN2917 supports a 2-wire, I²C-compatible serial bus, driving multiple peripherals. Two inputs, serial data (SDA) and serial clock (SCK), carry information between any devices connected to the bus. Each slave device is recognized by a unique address. The slave address consists of the seven MSBs of an 8-bit word. The upper six bits (Bits[6:1]) of the 7-bit slave address are factory programmed to 100000. The LSB of the slave address (Bit 0) is set by Pin 22, I²C_ADDR. The LSB of the word sets either a read or write operation (see Figure 13). Logic 1 corresponds to a read operation, whereas Logic 0 corresponds to a write operation.

To control the device on the bus, the following protocol must be used. First, the master initiates a data transfer by establishing a start condition, defined by a high to low transition on SDA while SCK remains high. This indicates that an address/data stream follows. All peripherals respond to the start condition and shift the next eight bits (the 7-bit address and the R/W bit). The bits are transferred from MSB to LSB. The peripheral that recognizes the transmitted address responds by pulling the data line low during the ninth clock pulse. This is known as an acknowledge bit. All other devices withdraw from the bus at this point and maintain an idle condition. The idle condition is when the device monitors the SDA and SCK lines waiting for the start condition and correct transmitted address. The R/W bit determines the direction of the data. Logic 0 on the LSB of the first byte means that the master writes information to the peripheral. Logic 1 on the LSB of the first byte means that the master reads information from the peripheral.

The ADN2917 acts as a standard slave device on the bus. The data on the SDA pin is eight bits long, supporting the 7-bit addresses plus the R/W bit. The ADN2917 has subaddresses to enable the user-accessible internal registers (see Table 7).

The ADN2917, therefore, interprets the first byte as the device address and the second byte as the starting subaddress. Auto-increment mode is supported, allowing data to be read from or written to the starting subaddress and each subsequent address without manually addressing the subsequent subaddress. A data transfer is always terminated by a stop condition. The user can also access any unique subaddress register on a one-by-one basis without updating all registers.

Stop and start conditions can be detected at any stage of the data transfer. If these conditions are asserted out of sequence with normal read and write operations, they cause an immediate jump to the idle condition. During a given SCK high period, issue one start condition, one stop condition, or a single stop condition followed by a single start condition. If an invalid subaddress is issued by the user, the ADN2917 does not issue an acknowledge and returns to the idle condition. If the user exceeds the highest subaddress while reading back in auto-increment mode, the highest subaddress register contents continue to be output until the master device issues a no acknowledge. This indicates the end of a read. In a no acknowledge condition, the SDA line is not pulled low on the ninth pulse. See Figure 14 and Figure 15 for sample write and read data transfers, respectively, and Figure 16 for a more detailed timing diagram.

REFERENCE CLOCK (OPTIONAL)

A reference clock is not required to perform clock and data recovery with the ADN2917. However, support for an optional reference clock is provided. The reference clock can be driven differentially or single-ended. If the reference clock is not being used, float both REFCLKP and REFCLKN.

Two 50 Ω series resistors present a differential load between REFCLKP and REFCLKN. Common mode is internally set to 0.56 × VCC by a resistor divider between VCC and VEE. See Figure 23, Figure 24, and Figure 25 for sample configurations.